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# Index

## A

- Abrasion, 10, 83
  - electrolytic, 91
  - ionic abrasion principles, 93–94
  - by mechanical polishing, 86
  - principle, 85–87
  - selective, 128, 130
- Absorption contrast, 46–47
- Acrylic resins, 110
- Aldehydes, 104–105
- Amorphous materials, 15, 27, 47
  - amplitude contrast, 47–48
- Amplitude contrast, 47–48
- Animal cell, 28
- Antigen–antibody reaction (Ag–Ab), 8
- Antiphase wall, 21
- Aqueous phase, elimination of, 98–99
  - approaches for treating hydrated samples, 99
  - arrangements of water molecule, 100
- Artifacts in TEM, 125–169
  - artifacts induced by
    - chemical fixation, 154–155
    - cryofixation technique, 158–159
    - cryo-ultramicrotomy technique, 140–147
    - electron beam, 164–167
    - extractive-replica technique, 155
    - fine particle dispersion technique, 159–161
    - freeze-fracture technique, 147–148
    - frozen-hydrated-film technique, 161–163
    - ion milling or FIB, 148–153
    - negative-staining, contrast technique, 163–164,
    - positive-staining, contrast technique, 157
    - shadowing technique, 156, 203

- substitution–infiltration–embedding technique, 154
    - tripod polishing technique, 137–140
  - formed by preliminary preparation techniques, 168
  - induced during observation, 135
    - artifacts not linked to thermal damages, 135–136
    - secondary thermal damage, 137
  - preparation-induced, 125
    - chemical, 131–134
    - ionic, 130–131
    - mechanical, 127–129
    - physical, 134–135
- Artificial material, 3
- Auger electrons, 36

## B

- Backscattered electrons, 35
- Bacteria, 29
- Bicrystalline, 15
- Biological materials, 3, 6, 8, 175, 177, 180–181
  - changes specific to, 132–133
  - 2D microstructures of, 28
  - 3D microstructures of, 27
  - microstructures in, 24–30
    - microstructure in biology, 27–30
    - problems to be solved in biology, 24–26
    - role of structures on functional properties, 30
    - singularity of biological materials, 26–27
  - physical materials vs., 6
- Bragg's law, 47
- Breaking point, 9
- Brittle materials, 84
- Brittle, of average brittleness, resistant, or ductile, materials, 12

- Bulk 3D materials at microscopic scale, organization of, 15
  - Bulk/multilayer materials, 176
    - comparison between all techniques used in biology on collagen, 229–233
    - comparison between different mechanical preparations, 207
      - Au/SiO<sub>2</sub>/Si sample, prepared using cleaved wedge method, 208
    - comparison between techniques specific to biology, 222–229
    - mechanical preparations vs. electrolytic preparations, 220–222
    - mechanical preparations vs. ionic preparations, 209–220
  - See also* Multilayer materials
- C**
- Carbide abrasion, 86
  - Carbohydrates, 26
  - Cathodic pulverization, 118–119
  - Cathodoluminescence, 35
  - CBED/LACBED diffraction modes, 72
  - Ceramics, 5, 175
    - hardnesses, 10
  - Chain flexibility, 12
  - Characterization, scales of, 58
  - Chemical bonds, 6–8
    - analysis, 182
    - covalent bonds, 7
    - ionic bonds, 7
    - and mechanical properties, 8–9
      - and crystallinity, 9
      - material hardnesses according to Mohs scale, 11
      - of organic materials and glass transition (*T<sub>g</sub>*), 12–13
      - rigidity: from hard to soft, 10
      - tensile strength: ductility–brittleness, 10–12
    - metallic bonds, 7
    - type of materials and, 8–13
    - weak nonpolar bonds, 7
    - weak polar bonds, 7
  - Chemical dissolution, 90
    - principle of, 90–93
    - techniques involving chemical dissolution, 92–93
  - Chemical fixation
    - artifacts induced by, 154–155
      - adipocyte cell, 154
      - portion of cell that has undergone double chemical fixation, 155
    - principle, 104–108
      - constancy of pH, 105–106
      - ionic concentration, 106–108
      - molar concentration, 106
  - Chemical mechanisms of preparation
    - techniques, *see* physical/chemical mechanisms of preparation techniques
  - Chemical preparation-induced artifacts, 131–134
    - changes specific to biological materials
      - change in chemical composition, 133
      - change in molecular bonds, 133
      - change in natural contrast, 133
      - protein cross-linking and changes in their spatial conformation, 133
      - residues, 133
      - structural change, 132
    - composition change, 132
    - matter displacement, 131
    - microstructural change, 132
    - secondary thermal damage induced
      - changes in phase distribution, 133
      - microstructural change, 133–134
    - selective dissolution, 132
    - structural change, 132
  - Chemical thinning, 172
  - Coating process, physics of
    - continuous thin film, formation, 113
      - stages, 114
    - different methods of particle production, 115–119
    - nature of chemical elements used as sources, 114–115
    - parameters, 114
    - substrate, 119
    - vacuum, 119
  - Collagen, 229–233
    - chemical fixation, embedding, ultramicrotomy, and positive-staining contrast, 232
    - comparison of chemical fixation/physical fixation/cryo-fixation, 232–233
    - comparison of negative-staining/decoration-shadowing contrast/freeze-fracture, 231–232
    - following high-pressure cryofixation and cryosubstitution, 233
    - after freeze fracture, sublimation, and replication, 232
    - negative-staining contrast vs. immunolabeling techniques, 229–230

- reconstituted, 231
  - rotary shadowing, 231
  - TEM images of, 66
  - Collagen 11, 230
  - Collagen fibers 2, 230
  - Composite materials, 8, 175, 178
  - Confocal microscopy, 59
  - Connective tissue, 29
  - Continuous/perforated thin film, 119–120
  - Contrast enhancement using shadowing/  
decoration, 120
  - Conventional transmission electron microscope  
(CTEM), 41–43
  - Convergent beam, 50
  - Covalent bonds, 7, 178
    - material with, 9
  - “Crossed Nichols” conditions, 59
  - Cross-linking, 133
  - Crushing, 87–90, 173
    - Pt catalyst on aluminum oxide Pt/Al<sub>2</sub>O<sub>3</sub>,  
thin slice obtained, 201
    - thin slice obtained using crushing  
technique, 200
  - Cryofixation technique, artifacts induced  
by, 158
    - rat liver cell slice, 158
    - using projection on cooled copper, 158
    - slice of liver frozen under high  
pressure, 159
  - Cryofracture, 224
  - Cryomicroscopy, 76–77, 136
    - structure of bulk frozen samples, 77
    - structure of isolated particles from  
biological materials or polymers,  
76–77
  - Cryo-sublimation (freeze-drying) principle,  
103–104
    - ice vapor pressure as function of  
temperature, 104
  - Cryo-ultramicrotomy, 88, 172–173, 229
    - cell prepared using fixation, 145
    - cross-section of SiO<sub>2</sub> fibers  
(ceramic), 142
    - diatom section, 141
    - isolated carbon particles (semi-crystalline),  
128
    - using chemical fixation, 145–146
  - Crystal defects
    - analysis of, 72, 181–182
    - in mixed-composite materials, 23
    - and properties of materials, 19–23
  - Crystalline point defect
    - dislocation loops, 20
    - interstitial, 20
    - vacancy, 20
  - Crystallographic analysis, 70–71, 181
  - Cutting, 86
  - Cytosol, 28–29
- D**
- Damage area, 84
  - Decoration-shadowing contrast technique, 173
  - Decoration technique, 120
  - Dedicated STEM, 45
  - Dehydration, 99
    - principles, 108
  - Deposition, physical actions resulting in
    - physical deposition, 112–113
    - physics of coating process, 113–119
    - techniques involving physical deposition,  
119–121
  - Desiccation, 99
  - 1 Dimensional crystal defect: dislocation, 21
  - 2 Dimensional crystal defects
    - coherent and semi-coherent interfaces, 22
    - grain boundaries, 22
  - 2 Dimensional microstructures of biological  
materials, 28
  - 3 Dimensional material and 2D projection of  
thin slice, 187
  - 3 Dimensional microstructures of biological  
materials, 27
  - 3 Dimensional volume defects, 21–23
  - Dimpling, 87
  - Double cupel technique
    - cryofracture at 123 K, 224
    - freeze fracture at 123 K, 226
  - Ductile materials, 85, 179
  - Ductility, 9, 85
- E**
- EDS, *see* Energy-dispersive spectrometry  
(EDS)
  - EDS chemical analysis and EELS spectro-  
scopic analysis, 73
    - concentration profiles and interface  
analysis, 74
    - phase identification and distribution, 73–74
  - EDS concentration profile across full interface  
of PbZrTiO<sub>3</sub>/substrate, 74
  - EDS detector, 51–52
  - Elasticity, 9
  - Electron beam, artifacts induced by, 164–167
  - Electrochemical dissolution, 90–93
    - electrolytic polishing principle, 91
    - selection of commercial polishing  
solutions, 92

- Electrochemical dissolution (*cont.*)  
 theories explaining, 91  
 techniques involving electrochemical dissolution, 92–93
- Electrochemical thinning, 93
- Electrolytic thinning, 172  
 ZrNi planar view, 221
- Electron beam-induced current (EBIC), 35
- Electron beam's path through convergent lens, 42
- Electron diffraction patterns, 71
- Electron-gun evaporator, 117
- Electron–material interaction  
 characteristics of responses to, 53  
 energy diagram of different signals emitted during, 34  
 signals derived from, 34
- Electron microscopy (SEM, TEM, STEM),  
 observation modes, 33  
 different types of microscopes: SEM, TEM, and STEM, 41  
 analytical TEM/STEM microscope and “dedicated stem,” 44–46  
 conventional transmission electron microscope (CTEM), 41–44  
 scanning electron microscope (SEM), 41  
 exploring range of energies emitted, 33  
 microscopes and observation modes, 39  
 illumination modes and detection limits, 39  
 illumination sources, 37–39  
 microscope resolutions and analysis, 39–40  
 signals used for electron microscopy  
 electron–matter interaction, 33–35  
 signals used for chemical analysis, 36  
 signals used for imaging, 35  
 signals used for structure, 37
- TEM observation modes  
 chemical contrast imaging modes in TEM and TEM/STEM, 49–50  
 contrast, 46–48  
 diffraction contrast imaging modes in TEM and TEM/STEM, 48  
 EDS chemical analysis methods in Tem and TEM/STEM, 51–52  
 EELS spectroscopic analysis modes in TEM and TEM/STEM, 52  
 spectroscopic contrast imaging modes in TEM and TEM/STEM, 50–51
- Electropolishing, 90, 93
- Embedding/inclusion principles, 110–111  
 properties of most commonly used infiltration–embedding/embedding resins, 111
- Energy-dispersive spectrometry (EDS), 36, 46, 49, 57
- Energy filters, different types of, 51
- Epitaxial layers, 113
- Epithelial tissues/nerve tissues, 29
- Epoxy resins, 109–110
- Eukaryotes, 28
- Evaporation  
 Joule-effect, 115–116  
 using electron gun, 116–117
- Excited volume, 34
- Extractive-replica technique, artifacts induced by, 155  
 catalyst containing particles of platinum on alumina substrate (Pt/Al<sub>2</sub>O<sub>3</sub>), 155  
 DNA molecules prepared by shadowing technique, 156  
 fragment of DNA molecules prepared by shadowing technique, 156  
 material prepared using, 202  
 Pt catalyst on aluminum oxide Pt/Al<sub>2</sub>O<sub>3</sub>, thin slice obtained, 201
- F**
- Fibroblast/extracellular glycoproteins  
 elastin/collagen, 227
- Fine particles, 107, 177  
 in biology, microstructures of, 28  
 dispersion technique, artifacts induced by, 159–161  
 dispersion of carbon nanotubes (polymer), 160  
 Pt/Ru/Sn (metal) powder dispersed on carbon film grid, 159  
 ZnO (ceramic) particles, 161  
 mechanical preparations vs. replicas, 199–202  
 negative-staining contrast vs. freeze-fracture techniques, 202–203  
 negative-staining vs. decoration-shadowing contrast techniques, 204–206  
 positive-staining vs. decoration-shadowing contrast techniques, 206–207
- Fine particles/single particles, organization of, 4, 14, 16, 65
- Focused ion beam thinning (FIB), 96–98, 213, 217  
 abrasion principles, 98  
 artifacts induced by, 148–153  
 dark field TEM using, 213

- gallium source, 97
  - image of thin slice, 211
  - ion source – gallium, 97
  - oxide/metal sample prepared in cross section, 210
  - type of, 97
  - See also* ion milling
  - Forces involved during cutting, 89
  - Fracture, 87
  - Freeze-fracture technique, 88, 173
    - artifacts induced by, 147–148
      - liver cell replica, 147
      - replica of cell showing nucleus, 148
  - Freezing diagram of organic solution of 300 mOsm in water, 102
  - Freezing principles, 100–102
  - Frozen-hydrated-film technique, artifacts induced by, 161–163
    - continuous frozen hydrated film presenting local small crystals of hexagonal ice, 162
    - crystals of cubic and hexagonal ice, 161 showing clusters of agglomerated crystals on edges of hole, 162
    - vitrified liposomes in frozen hydrated film, 163
- G**
- Gallium, as ion source of FIB, 96
  - Glass transition temperature, 12
  - Glutaraldehyde, 104–105
  - Golgi apparatus, 29
  - Grain boundaries, 21–22
    - two-dimensional crystal defects, 22
- H**
- Hardness, 9
    - materials and indication of possible preparation techniques, 180
  - Hard-resistant materials, 179–180
  - High-resolution electron microscopy (HRTEM), 48, 68–69
    - cross section in multilayer material, 72
    - multilayer Ru/Zr (2) on a SrTiO<sub>3</sub> substrate, 150
    - polycrystalline YBa<sub>2</sub>Cu<sub>3</sub>O<sub>7</sub>, 153
    - YBa<sub>2</sub>Cu<sub>3</sub>O<sub>7</sub> ceramic, 152
  - High rubbery polymers, 24
  - Hydrophobic bonds, *see* weak nonpolar bonds
- I**
- Imaging modes, diffraction contrasts in, 48
  - Immunolabeling technique, 173
  - Immunolocalization of epidermal proteoglycan in junction zone (j) of two keratinocytes, 228
  - Inclusion principles, *see* embedding/inclusion principles
  - Inelastic transmitted electrons (EELS or PEELS), 36
  - Infiltration principles, 108–110
    - infiltration resin, selecting, 109
  - In situ* analyses, TEM and TEM/STEM, 75
    - at high temperatures, 75–76
    - at low temperatures, 76
    - at room temperature, 75
  - Interfaces, 21
  - Ion beam thinning, 94
    - ion thinning principle, 96
    - selective etching as function of nature, 95
  - Ion bombardment, *see* ion milling
  - Ionic abrasion
    - principles, 93–94
      - artifacts generated, 94
      - yield of pulverization as function of acceleration voltage, 94
    - techniques involving, 94–98
  - Ionic bonds, 7, 178
    - material with, 9
  - Ionic preparation-induced artifacts, 130–131
    - cavities, 130
    - dislocation loops, 130
    - vacancies, 130
    - implantation, 130
    - microstructural change, 131
    - redeposition, 130
    - roughness, 130
    - secondary thermal damage induced during
      - amorphization, 131
      - demixing, 131
      - fusion, 131
      - loss of chemical elements, 131
      - phase transformation, 131
    - selective abrasion, 130
    - structural change, 130–131
  - Ion microscopy, 60
  - Ion milling, 172–173
    - artifacts induced by, 148–153
      - MgO bicrystal grain boundary, 149
      - Nb<sub>3</sub>Sn sample, 152
      - polycrystalline ceramic, 23, 148–149
      - YBa<sub>2</sub>Cu<sub>3</sub>O<sub>7</sub> ceramic, 151–152
    - YBa<sub>2</sub>Cu<sub>3</sub>O<sub>7</sub> matrix/Y<sub>2</sub>Ba–CuO<sub>5</sub> precipitate, 219
  - See also* focused ion beam thinning (FIB)

**J**

- Joule-effect evaporation, 115–116
  - device for carbon evaporation by, 116

**K**

- Knife and sample block, geometry, 89

**L**

- Linear defects, 19
- Living systems, 24–25
- Lowicryl resins, 103
  - temperatures of use, 103

**M**

- Macromolecules, isolated, 68
- Macroscopic characterization, 59
- Materials
  - approach for beginning investigation of, 61–63
  - classification and properties
    - type of materials and chemical bonds, 8–13
    - types of chemical bonds: atomic and molecular, 6–8
  - containing aqueous phase, actions resulting in state change of, 98
    - cryo-sublimation (or freeze-drying) principle, 103–104
    - elimination of aqueous phase, 98–99
    - freezing principles, 100–102
    - substitution/infiltration/embedding in cryogenic mode, 102–103
  - crystalline defects and properties of materials, 19–23
  - cutting directions
    - of bulk textured or polycrystalline material, 188
    - and sections based on nature of, 187
    - of single-layer and multilayer materials, 188
  - of different hardnesses and possible preparation techniques, 180
  - evolution of materials, 3–4
  - hardnesses according to Mohs scale, 11
  - microstructures, 13–24
    - investigations, problems, 4–6
    - problems to be solved, 4, 13–14
  - microstructures in biological materials
    - microstructure in biology, 27–30
    - problems to be solved in biology, 24–26
    - role of structures on functional properties, 30
    - singularity of biological materials, 26–27

- origin, 3
- parameters of, 4
- polymer microstructures, 18–19
- problems/approaches for TEM, *see* TEM and TEM/STEM analyses
- properties, actions resulting in
  - change in, 104
    - chemical fixation principle, 104–108
    - dehydration principles, 108
    - embedding or inclusion principles, 110–111
    - infiltration principles, 108–110
    - positive-staining contrast principles, 111–112
  - solid-state polymer properties, 23–24
  - study of properties using TEM, 77
    - chemical properties, 78
    - electrical properties, 77
    - electronic properties, 77–78
    - functional properties, 78
    - magnetic properties, 78
    - mechanical properties, 78
    - optical properties, 77
- Material's mechanical behavior, principles of, 84–85
  - brittle materials, 84
  - constant-volume deformation, 85
  - different steps of deformation, 84
  - ductile materials, 85
- Mechanical preparation-induced artifacts, 127–129
  - composition change, 129
  - cracks, 127
  - crystal-network change, 129
  - deformation, 127
  - dislocation, 127
  - fractures, 127
  - glide planes, 128
  - inclusion of abrasive grains, 127
  - matter displacement, 127
  - microstructural change, 128
  - residues, 129
  - roughness, 128
  - secondary thermal damage induced during
    - amorphization, 129
    - fusion, 129
    - loss of chemical elements, 129
    - phase transformation, 129
  - selective abrasion, 128
  - strain hardening, 128
  - structural change, 128
  - tearing of matter, 127
  - twinning, 128

- Metallic bonds, 7, 178
- Metallic materials, 8, 175
- Metals, 5
- hardnesses, 10
- Microcrystalline materials, 15, 17, 27
- Microscopes
- types – SEM/TEM/STEM, 41
  - analytical TEM/STEM microscope and “dedicated stem,” 44–46
  - conventional transmission electron microscope (CTEM), 41–43
  - scanning electron microscope (SEM), 41
- Microscopes and observation modes, 39
- illumination modes and detection limits, 39
  - illumination sources, 37–39
    - characteristics of different electron sources, 38
    - field emission guns (FEGs), 38–39
    - thermionic sources, 38  - microscope resolutions and analysis, 39–40
  - resolution limit of TEM, 39–40
  - spatial resolution, 40
- Microscopic characterization, 59–60
- and nanoscopic, 60–61
- Microscopic imaging modes – parallel beam/convergent beam, 50
- Microscopy, amplitude contrast/phase contrast, 48
- Microstructures, 14–17
- in biological materials
    - microstructure in biology, 27–30
    - problems to be solved in biology, 24–26
    - role of structures on functional properties, 30
    - singularity of biological materials: importance of liquid phase, 26–27  - geometry, 187–189
  - investigations, problems presented by, 4–6
  - in materials science
    - problems to be solved in, 13–14
- Milieu intérieur*, 26, 105–106
- Mineral materials, 8, 174
- Mixed–composite materials, 12, 65, 175
- Monocrystalline, 15, 17
- Multilayer materials, 5, 65, 178
- bright-field image of interface in, 75
  - See also* bulk/multilayer materials
- Muscle tissue, 29
- N**
- Natural materials, 3
- Negative-staining contrast, 113
- artifacts induced by, 163–164
- frozen hydrated film, 167
  - interface of Si-Fe/SiO<sub>2</sub> prepared using ultramicrotomy, 166
  - liposome suspension, 163
  - structure of SiO<sub>2</sub>, 166
  - superconducting ceramic, YBa<sub>2</sub>Cu<sub>3</sub>O<sub>7</sub>, 165
  - tobacco mosaic virus (TMV) in 5% uranyl acetate, 164
  - viral pseudo-particles using uranyl acetate, 164
  - vitrified liposomes in frozen hydrated film, 167
- physical deposition, 120–121
- technique, 173
- Neuron, TEM image, 68
- O**
- Observation modes in electron microscopy (SEM, TEM, STEM), 33
- microscopes and observation modes, 39
    - illumination modes and detection limits, 39
    - illumination sources, 37–39
    - microscope resolutions and analysis, 39–40
- SEM, TEM, and STEM microscopes, 41
- analytical TEM/STEM microscope and “dedicated stem,” 44–45
  - conventional transmission electron microscope (CTEM), 41–43
  - scanning electron microscope (SEM), 41
- signals used for electron microscopy
- electron–matter interaction, 33–35
  - signals used for chemical analysis, 36
  - signals used for imaging, 35
  - signals used for structure, 37
- TEM observation modes
- chemical contrast imaging modes, 49–50
  - contrast, 46–48
  - diffraction contrast imaging modes, 48
  - EDS chemical analysis methods, 51–52
  - EELS spectroscopic analysis modes, 52
  - spectroscopic contrast imaging modes, 50–51
- Omega filter, 51
- Organic matter, 8
- Oscillating quartz microbalance, 116
- Osmium tetroxide, 105

**P**

- Paraformaldehyde, 104–105
- Parallel beam, 50
- PEELS filter, 51
- Phase contrast, 47–48
- Physical/chemical mechanisms of preparation techniques, 83
  - actions resulting in change in material properties, 104
    - chemical fixation principle, 104–108
    - dehydration principles, 108
    - embedding or inclusion principles, 110–111
    - infiltration principles, 108–110
    - positive-staining contrast principles, 111–112
  - actions resulting in state change of materials containing aqueous phase, 98
    - cryo-sublimation (or freeze-drying) principle, 103–104
    - elimination of aqueous phase, 98–99
    - freezing principles, 100–102
    - principles of substitution, infiltration, and embedding in cryogenic mode, 102–103
  - chemical action
    - chemical/electrochemical dissolution principle, 90–93
  - ionic action
    - ionic abrasion principles, 93–94
    - techniques involving ion abrasion, 94–98
  - mechanical action
    - abrasion principle, 85–87
    - principles of material's mechanical behavior, 84–85
    - rupture principle, 87–90
  - physical actions resulting in deposition
    - physical deposition, 112–113
    - physics of coating process, 113–119
    - techniques involving physical deposition, 119–121
- Physical deposition, 112–113
  - techniques involving, 119–121
    - negative-staining contrast, 120–121
    - replica techniques, 120
- Physical materials vs. biological materials, 6
- Physical preparation-induced artifacts, 134–135
  - deformation, 134
  - microstructural changes, 134
  - secondary thermal damage induced
    - deformation, 134
    - frost, 135
    - fusion, 135
    - particle aggregation, 134
    - phase transformation, 135
- Plant cell, 29
- Plastic deformation, 85
- Point defects, 19
- Point EDS chemical analysis in PbZrTiO<sub>3</sub> film, 74
- Polycrystalline materials, 15, 17
- Polymers, 5, 176
  - different structures of, 18
  - hardnesses, 10
  - microstructures, 18–19
    - chain structure and flexibility, 19
  - structural investigation of, 66
  - structure of stabilized, 66
- Poorly organized materials, 15–16, 27
- Porous materials, 177
- Positive-staining contrast technique, 111–112, 173
  - artifacts induced by, 157
    - slice of cell showing spherical lead precipitates, 157
    - slice of embryonic cells from seedling, 157
- Preparation-induced artifacts, 125
  - chemical preparation-induced artifacts, 131–134
  - ionic preparation-induced artifacts, 130–131
  - mechanical preparation-induced artifacts, 127–129
  - physical preparation-induced artifacts, 134–135
- Preparation techniques based on material problems and TEM analyses, 171
  - adaptation of technique based on problems related to observation, 191
    - final cleaning of thin slice, 193
    - increasing contrast, 192
    - limitation of strain hardening, 192
    - reducing charge effects, 192
    - reducing sample thickness, 191–192
    - removal of surface amorphization, 192
    - removal of surface contamination, 192
  - based on material/type of analysis
    - bulk materials, 184
    - fine particles, 186
    - thin layer and multilayer materials, 185
  - characteristics of, 172–173
  - classification of, 171–172

- criteria used to select preparation technique, 173–174
  - direct methods, 172
    - techniques specific to bulk materials/multilayer materials/fine particles, 172
    - techniques specific to fine particles, 172
  - fine isolated particles of varying form in 3D view and 2D projections, 189
  - indirect methods, 172
  - sample preparation flow chart, 193
  - selecting technique based on material, 174
  - selection criteria based on material organization
    - bulk materials, 176
    - fine particles, 177
    - single-layer/multilayer materials, 176
  - selection criteria based on material properties
    - based on chemical phases in material, 177–178
    - based on electrical properties of material, 178
    - based on mechanical properties of material, 178–181
    - based on physical state of material, 177
  - selection criteria based on material type, 175–176
    - biological materials, 175
    - ceramics and minerals, 175
    - composite or mixed–composite material, 175
    - metallic materials, 175
    - polymers, 175
    - semiconductors, 175
  - selection criteria related to artifacts induced by preparation technique, 191
  - selection criteria related to type TEM analysis, 181–183
    - preparation techniques, 182–183
  - selection of orientation of sample section, 183–187
    - defect geometry, 189
    - microstructure geometry, 187–189
  - selection of preparation technique based on material and analysis type, 195
  - selection of preparation technique for bulk biological materials, 194
  - slice thickness based on observation mode and type of analysis, 190
- Prokaryotes, 28
- Proteins, 7
- Pulverization using ion gun, 117–118
- evaporator with ion gun, 118
- PZT ferroelectric film deposited by laser ablation, 64
- ## R
- Reduction–oxidation reaction (REDOX), 90
- Renal glomerulus, TEM image, 67
- Replica techniques, 173
  - physical deposition, 119–121
    - direct replica, 120
    - extractive replica, 120
    - freeze fracture, 120
    - indirect replica, 120
- Ribosomes, 29
- Rupture, 85
  - principle, 87–90
- ## S
- Sawing, 86
- Scanning electron microscope (SEM), 35
- Secondary electrons, 35
- Secondary thermal damage, 137
- Semiconducting materials, 8
- Semiconductors, 5, 175
  - hardness, 10
- Semi-crystalline polymer, 24
- Shadowing technique, artifacts induced by, 156
- Single-phase polycrystalline, Optical microscopic pictures, 60
- Solid-state
  - physics, materials in, 180
  - polymer properties, 23–24
- SrTiO<sub>3</sub> bicrystal grain boundary, 69
- STEM mode, 44, 49–50, 75
  - different detectors in, 45
- Sublimation, 99
- Substitution–infiltration–embedding technique artifacts induced by, 154
  - slice of *Staphylococcus aureus*, 154
  - in cryogenic mode, principles, 102–103
- Substrate, 119
- Surface precipitates in superconductor film of YBa<sub>2</sub>Cu<sub>3</sub>O<sub>7</sub>, 64
- ## T
- Techniques comparisons, 199
  - biology specific, 222–229
    - chemical fixation/cryo-embedding/immunolabeling, 227–228
    - chemical methods/physical methods/freeze-fracture, 222–224

- Techniques comparisons (*cont.*)
- immunolabeling/ultramicrotomy/  
cryo-ultramicrotomy, 228–229
  - collagen, 229–233
    - chemical fixation/physical  
fixation/cryo-embedding  
techniques, 232–233
    - negative-staining contrast vs.  
immunolabeling techniques,  
229–230
    - negative-staining/  
decoration-shadowing/  
freeze-fracture, 231–232
  - comparison between different mechanical  
preparations, 207–208
    - wedge cleavage technique vs. tripod  
polishing technique, 207–208
  - mechanical preparations vs. electrolytic  
preparations, 220–222
    - ZrNi planar view using electrolytic  
thinning, 221
  - mechanical preparations vs. ionic  
preparations, 209–220
    - cleaved wedge vs. ionic thinning, 209
    - tripod polishing/ion milling/FIB  
thinning, 215–218
    - tripod polishing + ions vs. FIB  
thinning, 210–213
    - tripod polishing vs. ion milling,  
218–219
    - ultramicrotomy vs. ion bombardment,  
214
  - mechanical preparations vs. replicas,  
201–203
    - crushing technique vs. extractive replica  
technique, 201–204
    - negative-staining vs.  
freeze-fracture techniques, 204
  - negative-staining contrast vs. freeze-  
fracture techniques, 204
  - negative-staining vs. decoration-shadowing  
contrast techniques, 204–207
  - chromatin prepared using negative  
staining, 206
  - chromatin prepared using unidirectional  
shadowing with platinum, 206
  - dark-field image of chromatin, 207
  - DNA after positive staining, 209
  - liposomes was frozen in nitrogen, 205
  - metallic rotary shadowing, 208
  - negative-staining, bright-field  
observation, 208
    - suspension of liposomes is treated using  
phosphotungstic acid, 205
  - positive-staining vs. decoration-shadowing  
contrast techniques, 206–207
  - wedge cleavage vs. ion milling  
techniques, 209
- TEM, *see* transmission electron microscopy  
(TEM)
- TEM analyses
- analyses conducted prior to, 57
  - assessment of, 81
  - scales of various, 61
  - selection of type of, 63
- TEM and TEM/STEM analyses, 57
- analyses conducted prior to TEM  
analyses, 57
    - macroscopic characterization, 59
    - microscopic and nanoscopic  
characterization, 60–61
    - microscopic characterization, 59–60
  - analysis of crystal defects, 72
  - analysis of topography, 63–64
  - approach for beginning investigation of  
material, 61–63
  - assessment of TEM analyses, 81
  - crystallographic analysis, 70–71
  - EDS chemical analysis and EELS  
spectroscopic analysis, 73
    - concentration profiles and interface  
analysis, 74–75
    - phase identification and  
distribution, 73
  - sample thickness and analysis of TEM and  
TEM/STEM, 81
  - selection of type of TEM analysis, 63
  - structural analyses in TEM
    - atomic structure, 68–70
    - morphology and structure of materials,  
64–68
  - structural analyses under special conditions
    - cryomicroscopy, 76–77
    - in situ analyses, 75–76
  - study of properties, 77
    - chemical properties, 78
    - electrical properties, 77
    - electronic properties, 77
    - functional properties, 78
    - magnetic properties, 78
    - mechanical properties, 78
    - optical properties, 77
- TEM observation modes
- artifacts induced during, 135

- artifacts not linked to thermal damages, 135–136
    - secondary thermal damage, 137
  - chemical contrast imaging modes, 49–50
  - contrast, 46–48
  - diffraction contrast imaging
    - modes, 48–49
  - EDS chemical analysis methods, 51–52
  - EELS spectroscopic analysis modes, 52
  - spectroscopic contrast imaging modes, 50–51
  - TEM/STEM microscope, 44
    - different types of detection in, 45
  - Tensile strength, 9
  - Textured ceramic, Optical microscopic pictures, 60
  - Textured materials, 68
  - Textured polycrystalline, 15, 27
  - Thermal damages
    - artifacts not linked to, 135–136
      - charging, 136
      - contamination, 136
      - dehydration, 135
      - destruction, 136
    - secondary
      - amorphization, 137
      - fusion (or sublimation), 137
      - loss of chemical elements, 137
      - migration, 137
      - phase transformation, 137
  - Thin layer or multilayer materials, 16–17
  - Tomography technique, 68
  - Topography
    - analysis of, 63–64
    - investigation, 181
  - Transmission electron microscopy (TEM), 1
    - biological research levels, 25
    - collagen fibers, 66
    - different observation scales, 62
    - different types of analyses, 80
    - methodological guide
      - (<http://temsamprep.in2p3.fr>), 1, 196–197
    - signals from electron–matter interaction
      - with thin sample, 37
    - structural analysis in
      - atomic structure, 68–70
      - morphology and structure of materials, 64–68
    - thicknesses required for structural/physical characterization, 79
  - Tripod polishing technique, 173, 212, 215, 220
    - artifacts induced by, 137–140
      - composite ceramic cross section, 139
      - cross-section of Si/SiO<sub>2</sub>/Ti/Pt/PZT/Pt material, 140
      - Cu/SiO<sub>2</sub>/S sample prepared, 153
      - germanium cross-section sample, 138
      - MgO single crystal, 137
      - SiO<sub>2</sub>/Au multilayer on Si substrate, 138
    - Au/SiO<sub>2</sub>/Si sample, 208
    - oxide/metal sample prepared in cross section, 210
    - planar view of ZrNi + CeO, 222
    - thinned material using, 212
    - YBa<sub>2</sub>Cu<sub>3</sub>O<sub>7</sub> matrix/Y<sub>2</sub>Ba–CuO<sub>5</sub> precipitate, 219
    - ZrNi planar view, 221
  - Tripod technique, 87
- ## U
- Ultramicrotomy, 88, 175, 214
    - artifacts induced by, 140–147
      - aluminum-based alloy, 144
      - biphase polymer prepared using ultramicrotomy, 140
      - cell prepared using chemical fixation, 145–146
      - cross-section of SiO<sub>2</sub> fibers (ceramic material), 142
      - diatom section, 141
      - isolated carbon particles (semi-crystalline), 143
      - liver cell prepared using chemical fixation, 146
      - multilayer DLC/Ti/Si<sub>3</sub>N<sub>4</sub>/Si (mixed-composite) material, 145
      - Si-Fe/SiO<sub>2</sub> (mixed-composite) particle, 144
      - slice of placenta, 147
      - slice of protozoan embedded in epoxy resin, 146
      - tin (*metal*) particle, 143
    - chemical fixation
      - substitution–impregnation and embedding in epoxy resin, 223
      - substitution–infiltration–embedding in epoxy resin, 225
    - planar view of ZrNi + CeO, 222
    - ultra-rapid high-pressure cryofixation/ cryosubstitution/ cryo-embedding in Lowicryl, 224, 226

Ultrasonic cutting, 86  
Ultrastructure, 67

**V**

Vacuum, 119  
Viruses, 30  
Vitreous ice, 101

**W**

Water phase diagram, 99  
Weak nonpolar bonds, 7  
Weak polar bonds, 7  
Website – <http://temsamprep.in2p3.fr>. (TEM, methodology guide), 1, 196

Wedge cleavage, 88, 173  
Au/SiO<sub>2</sub>/Si sample, 208  
Wedge tripod polishing method, 213

**X**

X-rays, 36, 60

**Y**

YBa<sub>2</sub>Cu<sub>3</sub>O<sub>7</sub> superconductive oxide, EDS and  
EELS spectra from, 73  
Yeasts, 29

**Z**

Zeiss TEM microscope, 42